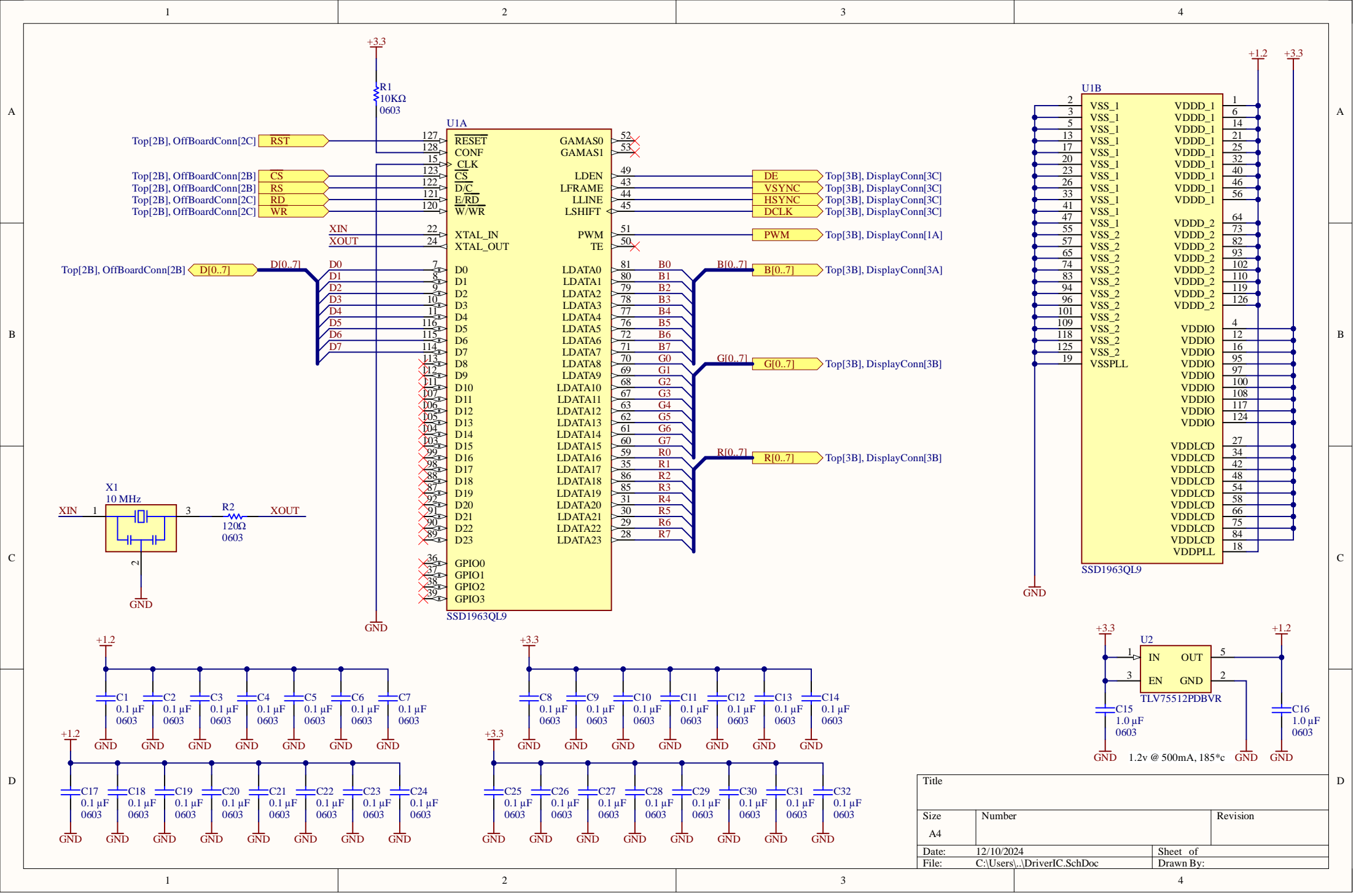
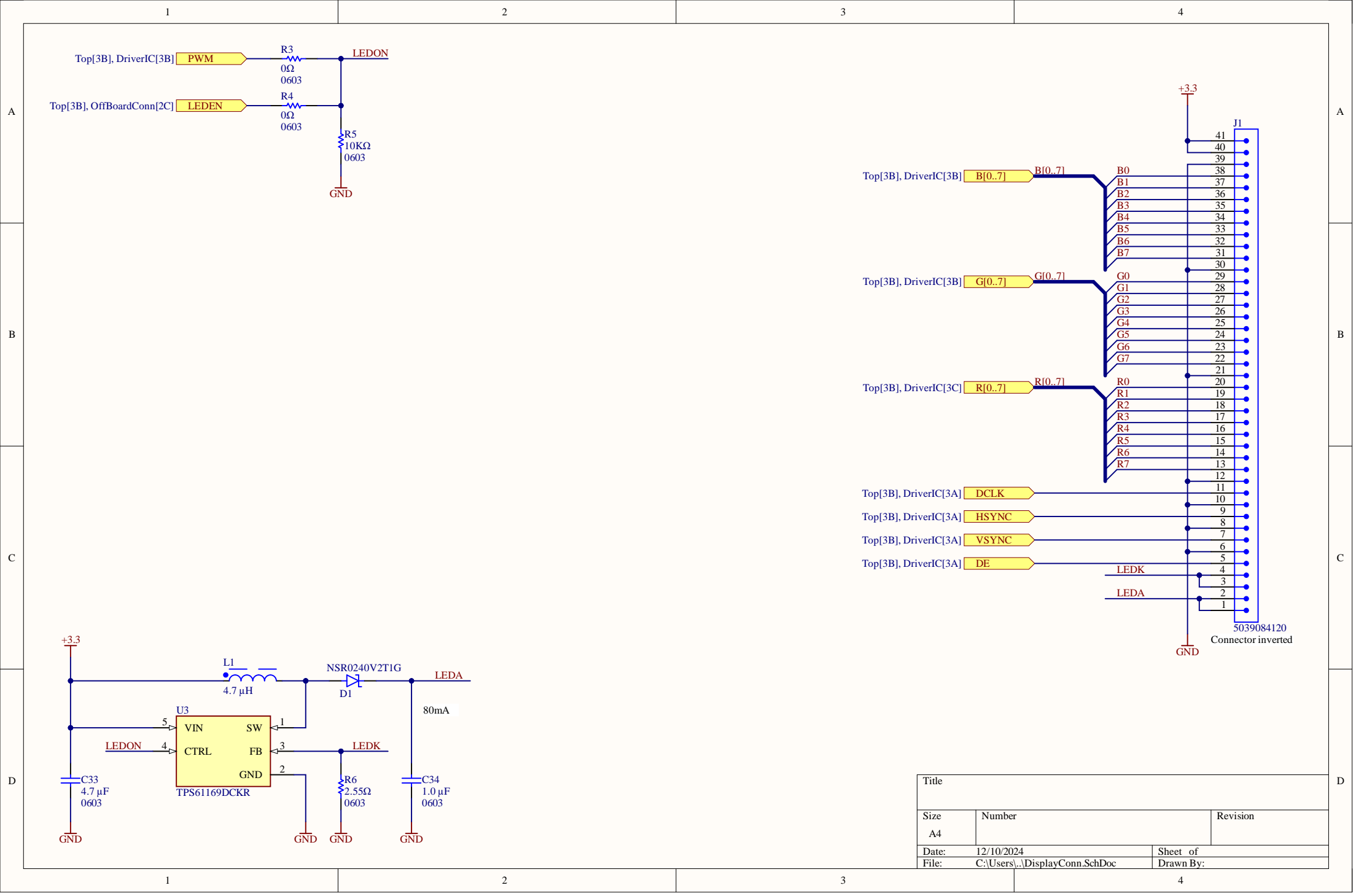
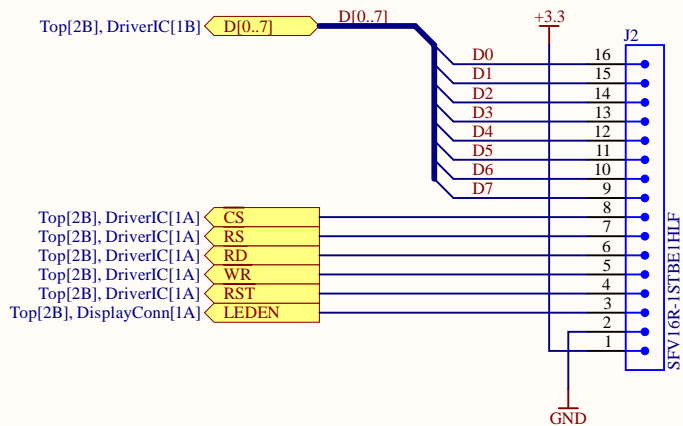


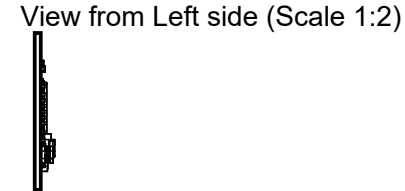
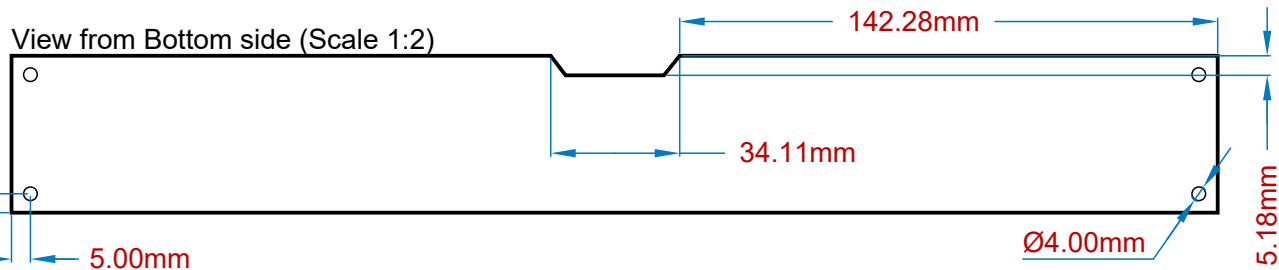
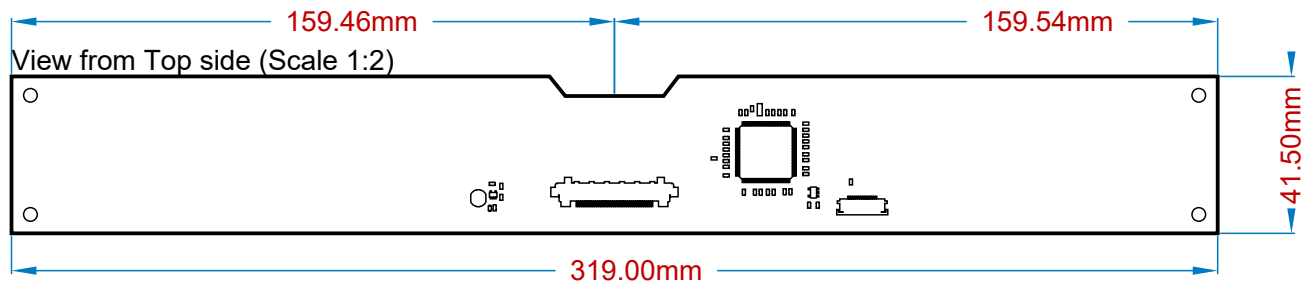
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Date:	12/10/2024	Sheet of
File:	C:\Users\...\Top.SchDoc	Drawn By:



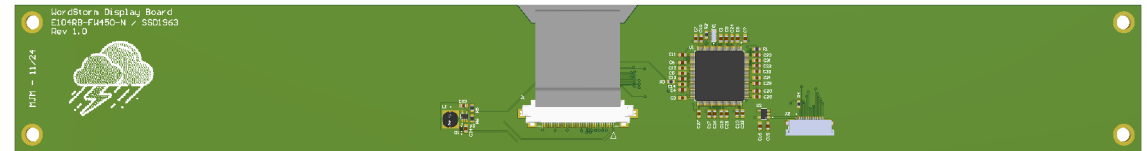




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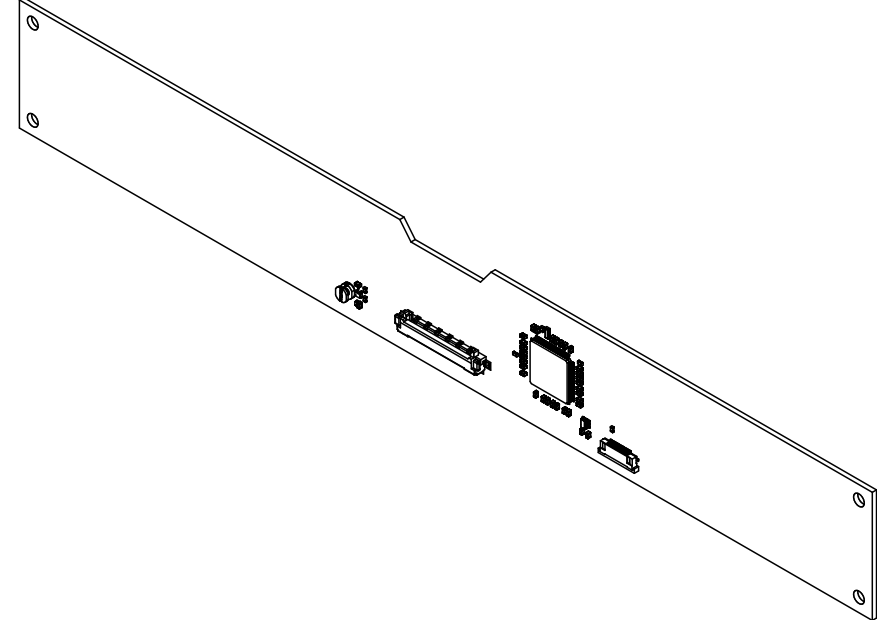
Realistic View



Realistic View



View from Top side (Scale 1:2)



Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.01mm(0mil)	Solder Resist	Solder Mask	GTS
Copper	Top Layer	0.04mm(1mil)		Signal	GTL
Prepreg		0.10mm(4mil)	2313	Dielectric	
Copper	Mid Layer 1	0.02mm(1mil)		Signal	G1
Core		1.26mm(50mil)	FR-4	Dielectric	
Copper	Mid Layer 2	0.02mm(1mil)		Signal	G2
Prepreg		0.10mm(4mil)	2313	Dielectric	
Copper	Bottom Layer	0.04mm(1mil)		Signal	GBL
Surface Material	Bottom Solder	0.01mm(0mil)	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
Total thickness: 1.60mm(63mil)					

USE: JLC04161H-3313 Stackup

